



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

ASAI et al.

Group Art Unit: 2841

Appln. No.: 09/529,597

Examiner: H. Bui

Filed: May 31, 2000

Title: PACKAGE SUBSTRATE

December 13, 2001

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AMENDMENT

Hon. Commissioner of Patents
Washington, D.C. 20231

Sir:

Responsive to the Office Action mailed on September 13, 2001, please amend the
patent application identified above as follows:

IN THE CLAIMS:

Please amend claim 1 as follows:

1. A package board having a core board on each surface of which a plurality of conductor circuits are formed with an interlaminar resin insulating layer therebetween, wherein a plurality of soldering pads are formed ^{on an IC chip} ~~on the IC chip~~ mounted side surface, as well ^{as on an other side surface} ~~as on the other side surface~~ to be connected to another board, so that said soldering pads on the other side surface are larger than those on said IC chip side surface of said package board, and
- 12/18/2001 RTYSON 00000001 033975 09529597
01 FC:102 168.08 dummy pattern for improving the mechanical strength of the package board is formed between signal line conductor circuit patterns formed on said IC chip mounted side surface of said core board.

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R. Tyson
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DEC 17 2001
TC 2800 MAIL ROOM

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